

# SV360

Leading in Vapor Phase Technology

Economy Vapor Phase Soldering Machine for Individual And Series Production

**IBL**



## The Machine

The SV360 reflow vapor phase soldering machine offers superior solder quality. It is ideal for soldering BGAs or LGAs and for prototype to series production..

## Overview

- Powerful front loader with small footprint
- 2-chamber design for low consumption
- Oxygen free soldering
- No overheating of components
- No  $\Delta T$ 's throughout the assembly

## Standard Equipment / Specification

- Comfortable operation with Touch Screen
- Automatic carrier in- and output
- Integrated cooling fan for board cooling
- Fully automatic solder cycle
- Adjustable solder automatic
- Energy management system
- Fluid level check
- Automatic liquid filtering
- Observation window to process chamber
- Integrated exhaust system

## Special features

- Maintenance-free transport system (**patented**)
- Easy access to process chamber
- Low fluid consumption with 2-chamber design and fluid recovery
- Program memory up to 50 programs
- Easy profil recording option

## Options

- Adapter for double sided PCB boards
- ReSy, a device for repair of QFP's and BGA's
- Stainless steel grid for the workpiece carrier
- Closed-loop-chiller
- TE-Option (2 channels) for external profile monitoring
- USB profiling system

Technical Data	SV360
Length (over all)	1450 mm
Depth	1000 mm
Height	1400 mm
Weight	345 kg
Max. board size	560 x 360 x 80 mm
Liquid agent filling	10 kg
Water connection	1/2" / 2,5-5 bar / 1,5 l/min
Max. heating capacity	5,2 kW
Ø power consumption/h	2,8 kW/h
Power supply	230/400 VAC 6 kW
Main fuse	16 A, Typ "gL" or "C"

- Technical changes reserved -

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